dicing width smaller than the diced groove of the semiconductor wafer.

15. A method of manufacturing a semiconductor device, comprising the steps of:

shaving a back surface of a semiconductor wafer, the back surface being opposite to an electrode-formed surface of the semiconductor wafer which includes a plurality of semiconductor elements;

dividing the semiconductor wafer into the semiconductor elements; and

bonding a reinforcing member to a back surface of each of the semiconductor elements with an adhesive.

16. The method of claim 15, further comprising the step of attaching a sheet to the electrode-formed surface of the semiconductor wafer, wherein said step of shaving the back surface of the semiconductor wafer includes the sub step of shaving the back surface of the semiconductor wafer to which the sheet is attached.

17. The method of claim 15, further comprising the step of forming a bump on the electrode-formed surface of the semiconductor wafer.

18. A method of mounting a semiconductor device which includes:

a semiconductor element having an electrode-formed surface;

a reinforcing member bonded to a back surface of the semiconductor element with allowing the semiconductor element to be deformed, the back surface being opposite the electrode-formed surface; and

an adhesive bonding the semiconductor element to the reinforcing member,

said method comprising the steps of:

holding the reinforcing member; and

mounting the semiconductor device to a workpiece, the semiconductor device having the reinforcing member held.

19. The method of claim 18,

wherein the reinforcing member includes a recess portion to which the semiconductor element is bonded and a projection formed at a border of the recess portion, and

wherein said step of mounting the semiconductor device includes the sub step of bonding the projection to the workpiece.